

L Number	Hits	Search Text	DB	Time stamp
1	1456	216/13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
2	1042	216/20	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
3	658	216/33	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
4	211	216/34	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
5	182	216/35	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
6	1360	216/41	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
7	526	216/49	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
8	3063	216/67	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
9	885	216/83	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
10	1	216/100-109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
11	3420	216/100-109.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:37
12	207	216/95	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:38

13	10550	216/13 216/20 216/33 216/34 216/35 216/41 216/49 216/67 216/83 216/100-109.ccls. 216/95	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:38
14	100	(216/13 216/20 216/33 216/34 216/35 216/41 216/49 216/67 216/83 216/100-109.ccls. 216/95) and polyimide near2 polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:38
15	34	(216/13 216/20 216/33 216/34 216/35 216/41 216/49 216/67 216/83 216/100-109.ccls. 216/95) and polyimide near2 polyimide with (metal metallization metallized copper aluminum cu al conductive conductor wiring circuit circuitry conducting circuitized)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:50
16	141	polyimide near1 adhesive with metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:51
17	41	(polyimide near1 adhesive with metal) with laminat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/06 16:53